



NOTES:

1. MATERIAL:

- 1.1 HOUSING: NYLON UL94V-0
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FITTING NAIL: COPPER ALLOY
- 1.4 COVER TYPES:  
COVER-C2 : STAINLESS STEEL  
COVER-C3 : NYLON UL94V-0  
COVER-C : NYLON UL94V-0

2. FINISH:  
UNDER PLATING: 50 $\mu$  MIN. NICKEL OVERALL  
CONTACT AREA AND SOLDER TAIL: MATTE TIN 100 $\mu$  MIN. OVERALL  
FITTING NAIL:  
UNDER PLATING: 50 $\mu$  MIN. NICKEL OVERALL  
MATTE TIN PLATING 100 $\mu$  MIN. OVERALL

3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP.  
FOR 10 SECONDS MAX.

4. SPEC. PLS. REFER TO GS-12-572.

5. PACKAGE PLS. REFER TO GS-14-1314.

6. PART NUMBER DESCRIPTION:  
10089715-XXX 0 0 0 LF

LEAD FREE COLOR  
0: NATURAL

NO OF CONTACTS  
PACKING  
0: TAPE REEL  
PLATING  
0: MATTE TIN

CKT	Dim.A	Dim.B	Dim.C	Dim.D
004	3.0	4.4	6.0	4.5
005	4.0	5.4	7.0	5.0
006	5.0	6.4	8.0	4.8
007	6.0	7.4	9.0	5.0
008	7.0	8.4	10.0	5.0
010	9.0	10.4	12.0	5.0
012	11.0	12.4	14.0	5.0

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI	www.fciconnect.com
ltr	ecn no	dr	date	linear	angles			
E	T09-1108	WL	08/19/09	.XX ± 0.25		projection	title 1.0mm WIRE TO BOARD CONN. WAFER SMT S/T TYPE	
F	T09-1151	WL	11/25/09	.XX ± 0.15				
G	T10-0004	WL	01/05/10	.XXX ± 0.10	0° ± 2°	MM		
H	T10-0064	WL	05/17/10	dr	LEIF SHEN 06/18/08	scale	product family size	WIRE TO BOARD
				engr	LEIF SHEN 06/18/08		dwg no	code
				chr	LEIF SHEN 06/18/08		A4	TWN
				appd	JOSEPH HSIA 06/18/08			sheet
								1 of 1
sheet index	revision sheet	H						
			1					